

SHARP

OPTO-ELECTRONIC DEVICES DIVISION ELECTRONIC COMPONENTS GROUP SHARP CORPORATION

SPECIFICATION

	DEVICE SPECIFICATION FOR	
	PHOTOINTERRUPTER MODEL No.	
	GP1S093HCZ0F	
	Specified for	
After con	I please find copies of the Specifications which consists of immation of the contents, please be sure to send back [roving signature on each.	of 10 pages including cover. copies of the Specifications
CUSTO	MER'S APPROVAL	PRESENTED
DATE	3	DATE
BY		BY / ()
		H. Ogura, Department General Manager of Engineering Dept., III Opto-Electronic Devices Div.

ELECOM Group SHARP CORPORATION <u>Product name: PHOTOINTERRUPTER</u>

Model No.: GP1S093HCZ0F

- 1. These specification sheets include materials protected under copyright of Sharp Corporation ("Sharp"). Please do not reproduce or cause anyone to reproduce them without Sharp's consent.
- When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets, as well as the precautions mentioned below. Sharp assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets, and the precautions mentioned below.

(Precautions)

- (1) This product is designed for use in the following application areas;
 - · OA equipment · Audio visual equipment · Home appliances
 - Telecommunication equipment (Terminal) Measuring equipment
 - Tooling machines
 Computers

If the use of the product in the above application areas is for equipment listed in paragraphs (2) or (3), please be sure to observe the precautions given in those respective paragraphs.

- (2) Appropriate measures, such as fail-safe design and redundant design considering the safety design of the overall system and equipment, should be taken to ensure reliability and safety when this product is used for equipment which demands high reliability and safety in function and precision, such as;
 - Transportation control and safety equipment (aircraft, train, automobile etc.)
 - Traffic signals Gas leakage sensor breakers Rescue and security equipment
 - · Other safety equipment
- (3) Please do not use this product for equipment which require extremely high reliability and safety in function and precision, such as;
 - · Space equipment · Telecommunication equipment (for trunk lines)
 - · Nuclear power control equipment · Medical equipment
- (4) Please contact and consult with a Sharp sales representative if there are any questions regarding interpretation of the above three paragraphs.
- 3. Please contact and consult with a Sharp sales representative for any questions about this product.



1. Application

This specification applies to the outline and characteristics of transmissive type photointerrupter; Model No. GP1S093HCZ0F.

- 2. Outline: Refer to the attached drawing No. CY10872i02.
- 3. Ratings and characteristics: Refer to the attached sheet, Page 4, 5.
- 4. Reliability: Refer to the attached sheet, Page 6.
- 5. Outgoing inspection: Refer to the attached sheet, Page 7.
- 6. Supplements
 - 6.1 Parts: Refer to the attached sheet, Page 8.
 - 6.2 Packing: Refer to the attached drawing No. SOE001327.
 - 6.3 ODS materials

This product shall not contain the following materials.

Also, the following materials shall not be used in the production process for this product.

Materials for ODS : CFC_S, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methyl chloroform)

6.4 Brominated flame retardants

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this device at all.

6.5 RoHS restriction

This product corresponds to the RoHS directive,

6.6 Product mass: Approx. 50mg

7. Notes

1) Circuit design

In circuit designing, make allowance for the degradation of the light emitting diode output that results from long continuous operation. (50% degradation/5 years)

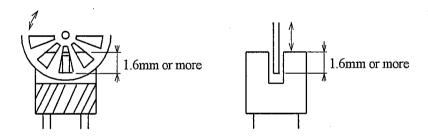
2) Prevention of faulty operation

To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.

3) Position of opaque board

Opaque board shall be installed at place 1.6mm or more from the top of elements.

(Example)



4) Soldering

To solder onto lead pins, solder at the position of 1mm or more from the package's bottom at 260°C for 5 s or less.

Please don't bend lead pins from the root of package when soldering.

And please take care not to let any external force exert on lead pins.

Please don't do soldering with preheating, and please don't do soldering by reflow.

5) Cleaning

Cleaning shall be carried out as below to avoid remaining of solvent, solder and flux on the device.

- (1) Solvent cleaning: Solvent temperature 45°C or less, Immersion for 3 min or less
- (2) Ultrasonic cleaning: Please don't carry out ultrasonic cleaning.
- (3) The cleaning shall be carried out with solvent below.

Solvent: Ethyl alcohol, Methyl alcohol

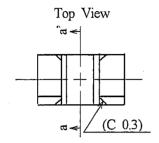
6) Lead pin

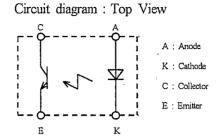
Lead terminals of this product are plated with tin copper alloy. Before usage, please evaluate solderability with actual conditions and confirm. And the uniformity in color for the lead terminals are not specified.

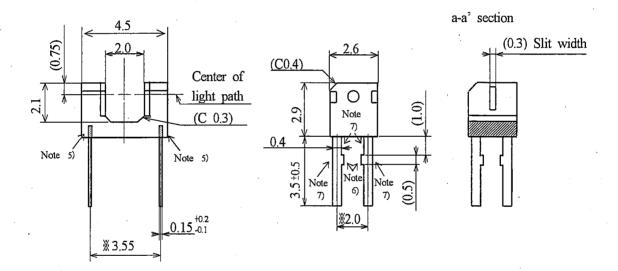
2. Outline Dimensions (Drawing No. CY10872i02)

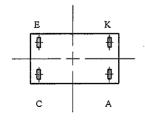
Scale : 5/1

Unit: 1/1mm









Note

- 1) Unspecified tolerance shall be ± 0.2 .
- 2) Dimensions in parenthesis are shown for reference.
- 3) The dimensions indicated by \times refer to the those measured from the lead base.
- The dimensions shown do not include those of burrs.
 Burr's dimensions shall be 0.15 MAX...
- 5) The lead may be exposed at the shaded portion.
- 6) This portion has no solder plating.
- 7) This portion does not have any solder plating in some cases.

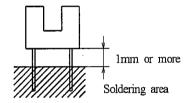
3. Ratings and characteristics

3.1 Absolute maximum ratings

Ta=25℃

	Parameter	Symbol	Rating	. Unit
	Forward current	I _F	50	mA
Input	Reverse voltage	V_R	6	V
	Power dissipation	P	75 ·	mW
	Collector-emitter voltage	V _{CEO}	35	V
Outrest	Emitter-collector voltage	V _{ECO}	6	V
Output	Collector current	Ic	20	mA
	Collector power dissipation	Pc	75	mW
	Total power dissipation	Ptot	100	mW
	Operating temperature	Topr	-25 to +85	℃
	Storage temperature	Tstg	-40 to +100	°C
	* Soldering temperature	Tsol	260	°C

Soldering time: 5 s or less

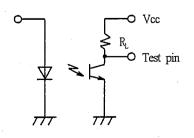


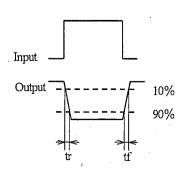
3.2 Electro-optical characteristics

Ta=25°C

	Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
т.,	Forward voltage		V _F	I _F =20mA	-	1.2	1.4	V
Input	Reverse current		I_R	V _R =3V	-	-	10	μΑ
Output	Collector dark curr	ent	I_{CEO}	V _{CE} =20V	-	-	100	пA
	Collector current		Ic	V_{CE} =5V, I_F =5mA	100	-	400	μΑ
Transfer	Response time	(Rise)	tr	V_{CE} =5V, Ic=100 μ A	-	50	150	μs
character- istics		(Fall)	tf	$R_L=1k\Omega$	-	50	150	μs
	Collector-emitter saturation voltage		V _{CE} (sat)	I _F =10mA, Ic=40 μ A	-	_	0.4	V

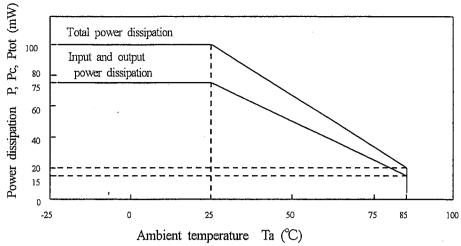
(Test circuit for response time)



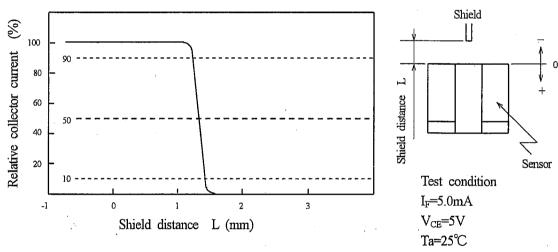


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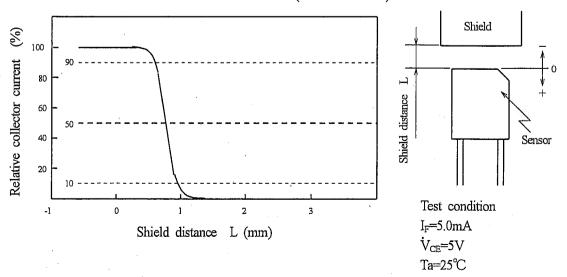
Power dissipation vs. ambient temperature



Relative collector current vs. shield distance 1 (Reference value)



Relative collector current vs. shield distance 2 (Reference value)





4. Reliability

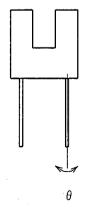
The reliability of products shall satisfy items listed below.

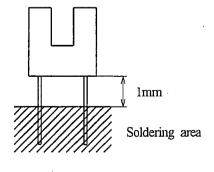
Confidence level : 90%

LTPD: 10 or 20

m , I,	T C. I'.'	T-1 - I 1	Samples (n)
Test Items	Test Conditions	Failure Judgement Criteria	Defective (c)
Temperature cycling	1 cycle -40°C to +100°C (30min) (30min) 20 cycles test		n=22, c=0
humidity storage	+60°C, 90%RH, 500h	·	n=22, c=0
High temp. storage	+100°C, 500h		n=22, c=0
Low temp. storage	-40°C, 500h	I _R ≧U×2	n=22, c=0
Operation life	I _F =20mA, Ta=25°C, 500h	I _{ŒO} ≧U×2	n=22, c=0
Mechanical shock	15000m/s ² , 0.5ms 3 times/±X, ±Y, ±Z direction	$V_F \ge U \times 1.2$	n=11, c=0
Variable frequency vibration	100 to 2000 to 100Hz/20min 2h/X, Y, Z direction 100m/s ²	Ic≦L×0.8	n=11, c=0
Terminal strength (Tension)	Weight: 3.0N 30s/each terminal	U: Upper specification limit	n=11, c=0
Terminal strength (Bending) *1	Weight: 1.0N $0^{\circ} \rightarrow 90^{\circ} \rightarrow 0^{\circ} \rightarrow -90^{\circ} \rightarrow 0$ 1 time bending	L. Lower specification limit	n=11, c=0
Soldering heat *2	260°C, 5s Immerse up to 1mm from the bottom face of package.		n=11, c=0
Solderability *2, *3	245°C, 3s Prior disposition: Dip rogin flux. Then immerse up to 1mm from the bottom face of package.	Judgement only appearance Solder shall adhere at less than 95% area of immersed portion of lead.	n=11, c=0

^{*} Terminal bending direction is shown below.





*3 The alloy composition of solder used for lead free should be Sn-2.5Ag-1Bi-0.5Cu or Sn-3.0Ag-0.5Cu. Flux used for precleaning should be equivalent to EC-19S(TAMURA KAKEN CORPORATION).

^{*} Soldering area is shown below.

- 5. Outgoing inspection
- 5.1 Inspection items
- (1) Electrical characteristics

 V_F , I_R , BV_{ECO} , BV_{CEO} , I_C , I_{CEO} , $V_{CE(sat)}$

- (2) Appearance
- 5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on ISO 2859 is applied. The AQL according to the inspection items are shown below.

Defect	Inspection item	AQL(%)
Major defect	Characteristics defect	0.065
Minor defect	Defects on appearance except shown above. *	0.25

* Crack ··· Visible crack shall be defect.

Split

* Chip

··· One which affects the electrical characteristics shall be defect.

Scratch

The others



6. Supplements

6.1 Parts

This product uses the below parts.

6.1.1 Light detector (Quantity: 1)

Туре	Material	Maximum sensitivity (nm)	Sensitivity (nm)	Response time (μs)
Phototransistor	Silicon (Si)	930	700 to 1200	20

6.1.2 Light emitter (Quantity: 1)

Туре	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared light emitting diode (non-coherent)	GaAs	950	0.3

6.1.3 Material

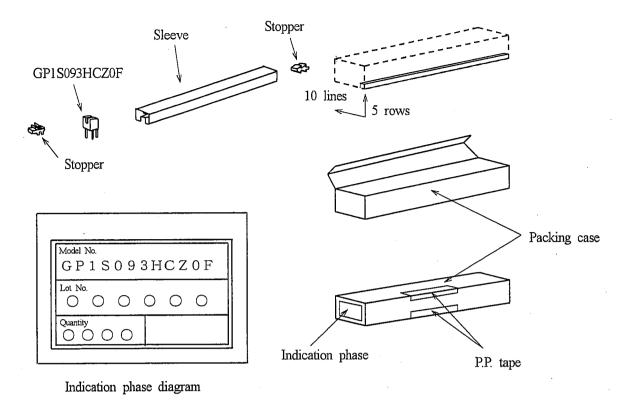
Case	Lead frame	Lead frame plating	
Black PPS resin (UL 94V-0)	42 Alloy	SnCu plating	

6.1.4 Others

This product shall not be proof against radiation flux.

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6.2 Package (Drawing No.: SOE001327)



1) Package materials

Outer package: Packing case (Corrugated cardboard)

Inner package: Sleeve (Polystyrene)

Stopper (Styrene-Elastomer)

Packaging numbers
 MAX. 100 pieces per sleeve
 MAX. 5,000 pieces per case

3) Package specifications

Arranges in 5 rows in 10 lines of sleeves containing GP1S093HCZ0F into the outer case. Closes the lid of outer case and seals with P.P. tapes.

4) Indication items
Indicates on the outer case "Model No.", "Lot No.", "Quantity" and "Inspection date".

5) Regular packing mass

(Excluding fractions, however above packing material, packing count, packing style)

Approx. 790g